Icemos Technology Ltd Product Specification 1000.703502 Issue Date 20 December 2023 11

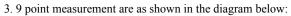
Part Number	Customer

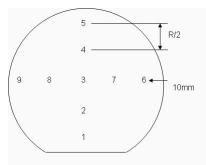
Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110}+/-1.0 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none / semi std	
	5.0	Overall Thickness	422.00 +/- 11.00 μm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<5.00μm	Guaranteed by Process
	7.0	Bow	<60.00μm	ADE to ASTM F534, 100%
	8.0	Warp	<60.00μm	ADE to ASTM F657, 100%
	9.0	Edge Chips	0	Bright Light, 100%
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	CZ	Wafer Vendor
	12.0	Handle Orientation	{100} +/- 1.0 degree	Wafer Vendor
	13.0	Handle Thickness	400.00 +/- 10.00 μm	ADE, 100%
	14.0	Handle Doping Type	N	Wafer Vendor
	15.0	Handle Dopant	Phosphorus	Wafer Vendor
	16.0	Handle Resistivity	0.01~0.05 Ohm-cm	Wafer Vendor
	17.0	Backside Finish	Polished with oxide and lasermark	Wafer Vendor
BuriedOxide	18.0	Oxide Type	Thermal	
	19.0	Oxide Thickness	20,000.00 +/- 1,000.00 A	Nanospec centre point, 4%
	20.0	Oxide formed on	Handle and/or device wafer	
DeviceSilicon	21.0	Device Growth Method	CZ	Wafer Vendor
	22.0	Device Orientation	{100} +/- 1.0 degree	Wafer Vendor
	23.0	Nominal Thickness	20.00 +/- 0.50 μm	ADE Single point, 100%
	24.0	Distance to device silicon edge from wafer edge	<= 2mm	Typical by Process
	25.0	Device Doping Type	N	Wafer Vendor
	26.0	Device Dopant	Phosphorus	Wafer Vendor
	27.0	Device Resistivity	0.01~0.05 Ohm-cm	Wafer Vendor
	28.0	Voids	0	Bright Light, 100% (note 2)
	29.0	Scratches	0	Bright Light, 100% (note 2)
	30.0	Haze	none	Bright Light, 100% (note 2)

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icemos recimology	Lu	Toduct Specification	1000.703302	Issue Date	20 December 2023 11
Part Number		Customer			
Category	Parameter	Specification		Me	easurement Method
Shipping Details	Wafer per box :	Max 25			
	Packaging:	Taped Polypropylene Wafer Bo Empak, Ultrapak, 100.00mm Antistatic Double Bagging	Σ		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness			
Explanatory Notes	1. Microscope inspec	tion performed using microscope so	can as below. 5x objec	tive.	
		pections performed exclude all wafe	_		ed in Overall

Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.





Additional Information